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Applications of "<u>Embedded - Microcontrollers</u>"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	40MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, HLVD, POR, PWM, WDT
Number of I/O	25
Program Memory Size	32KB (16K x 16)
Program Memory Type	FLASH
EEPROM Size	256 x 8
RAM Size	1.5K x 8
Voltage - Supply (Vcc/Vdd)	2V ~ 5.5V
Data Converters	A/D 10x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	28-VQFN Exposed Pad
Supplier Device Package	28-QFN (6x6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic18lf2523t-i-ml

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28/40/44-Pin, Enhanced Flash Microcontrollers with 12-Bit A/D and nanoWatt Technology

Power Management Features:

- · Run: CPU on, Peripherals on
- · Idle: CPU off, Peripherals on
- · Sleep: CPU off, Peripherals off
- Ultra Low 50 nA Input Leakage
- Run mode Currents Down to 11 μA Typical
- Idle mode Currents Down to 2.5 μA Typical
- Sleep mode Current Down to 100 μA Typical
- · Timer1 Oscillator: 900 nA, 32 kHz, 2V
- Watchdog Timer: 1.4 μA, 2V Typical
- Two-Speed Oscillator Start-up

Flexible Oscillator Structure:

- · Four Crystal modes, up to 40 MHz
- 4x Phase Lock Loop (PLL) Available for Crystal and Internal Oscillators
- · Two External RC modes, up to 4 MHz
- Two External Clock modes, up to 40 MHz
- · Internal Oscillator Block:
 - Fast wake from Sleep and Idle, 1 μs typical
 - 8 user-selectable frequencies, from 31 kHz to 8 MHz
 - Provides a complete range of clock speeds, from 31 kHz to 32 MHz, when used with PLL
- User-tunable to Compensate for Frequency Drift
- Secondary Oscillator using Timer1 @ 32 kHz
- Fail-Safe Clock Monitor:
 - Allows for safe shutdown if peripheral clock stops

Peripheral Highlights:

- 12-Bit, Up to 13-Channel Analog-to-Digital Converter module (A/D):
 - Auto-acquisition capability
 - Conversion available during Sleep mode
- Dual Analog Comparators with Input Multiplexing
- High-Current Sink/Source 25 mA/25 mA
- Three Programmable External Interrupts
- Four Input Change Interrupts
- Up to Two Capture/Compare/PWM (CCP) modules, One with Auto-Shutdown (28-pin devices)
- Enhanced Capture/Compare/PWM (ECCP) module (40/44-pin devices only):
 - One, two or four PWM outputs
 - Selectable polarity
 - Programmable dead time
- Auto-shutdown and auto-restart

Peripheral Highlights (Continued):

- Master Synchronous Serial Port (MSSP) module Supporting 3-Wire SPI (all four modes) and I²C™ Master and Slave modes
- · Enhanced USART module:
 - Support for RS-485, RS-232 and LIN/J2602
 - RS-232 operation using internal oscillator block (no external crystal required)
 - Auto-wake-up on Start bit
 - Auto-Baud Detect (ABD)

Special Microcontroller Features:

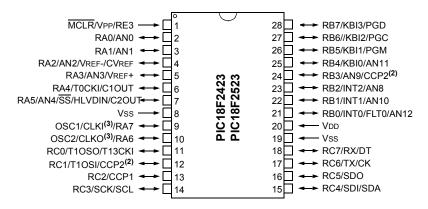
- C Compiler Optimized Architecture: Optional Extended Instruction Set Designed to Optimize Re-Entrant Code
- 100,000 Erase/Write Cycle, Enhanced Flash Program Memory Typical
- 1,000,000 Erase/Write Cycle, Data EEPROM Memory Typical
- Flash/Data EEPROM Retention: 100 Years Typical
- · Self-Programmable under Software Control
- · Priority Levels for Interrupts
- 8 x 8 Single-Cycle Hardware Multiplier
- Extended Watchdog Timer (WDT): Programmable Period, from 4 ms to 131s
- Single-Supply In-Circuit Serial Programming™ (ICSP™) via Two Pins
- · In-Circuit Debug (ICD) via Two Pins
- Operating Voltage Range: 2.0V to 5.5V
- Programmable, 16-Level High/Low-Voltage Detection (HLVD) module: Supports Interrupt on High/Low-Voltage Detection
- Programmable Brown-out Reset (BOR): With Software-Enable Option

Note: This document is supplemented by the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631). See Section 1.0 "Device Overview".

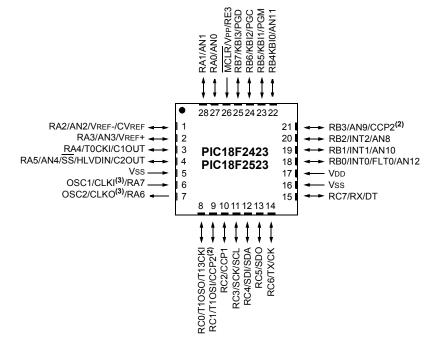
	Prog	ram Memory	Data	Memory		40 D''	CCP/	MS	SSP	RT		T
Device	Flash (bytes)	# Single-Word Instructions	SRAM (bytes)	EEPROM (bytes)	I/O	12-Bit A/D (ch)	ECCP (PWM)	SPI	Master I ² C™	EUSA	Comp.	Timers 8/16-Bit
PIC18F2423	16K	8192	768	256	25	10	2/0	Υ	Υ	1	2	1/3
PIC18F2523	32K	16384	1536	256	25	10	2/0	Υ	Υ	1	2	1/3
PIC18F4423	16K	8192	768	256	36	13	1/1	Υ	Υ	1	2	1/3
PIC18F4523	32K	16384	1536	256	36	13	1/1	Υ	Υ	1	2	1/3

Pin Diagrams

28-Pin PDIP, SOIC



28-Pin QFN⁽¹⁾



- Note 1: It is recommended to connect the bottom pad of QFN package parts to Vss.
 - 2: RB3 is the alternate pin for CCP2 multiplexing.
 - 3: OSC1/CLKI and OSC2/CLKO are only available in select oscillator modes and when these pins are not being used as digital I/O. For additional information, see Section 2.0 "Oscillator Configurations" of the "PIC18F2420/2520/4420/4520 Data Sheet" (DS39631).

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An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

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1.2 Other Special Features

- 12-Bit A/D Converter: This module incorporates programmable acquisition time, allowing for a channel to be selected and a conversion to be initiated without waiting for a sampling period, thereby reducing code overhead.
- Memory Endurance: The Enhanced Flash cells for both program memory and data EEPROM are rated to last for many thousands of erase/write cycles – up to 100,000 for program memory and 1,000,000 for EEPROM. Data retention without refresh is conservatively estimated to be greater than 40 years.
- Self-Programmability: These devices can write
 to their own program memory spaces under internal software control. By using a bootloader routine
 located in the protected Boot Block at the top of
 program memory, it is possible to create an
 application that can update itself in the field.
- Extended Instruction Set: The PIC18F2423/ 2523/4423/4523 family introduces an optional extension to the PIC18 instruction set that adds eight new instructions and an Indexed Addressing mode. This extension, enabled as a device configuration option, has been specifically designed to optimize re-entrant application code originally developed in high-level languages, such as C.
- Enhanced CCP module: In PWM mode, this
 module provides one, two or four modulated
 outputs for controlling half-bridge and full-bridge
 drivers. Other features include auto-shutdown, for
 disabling PWM outputs on interrupt or other select
 conditions, and auto-restart, to reactivate outputs
 once the condition has cleared.
- Enhanced Addressable USART: This serial communication module is capable of standard RS-232 operation and provides support for the LIN/J2602 bus protocol. Other enhancements include automatic baud rate detection and a 16-bit Baud Rate Generator for improved resolution. When the microcontroller is using the internal oscillator block, the EUSART provides stable operation for applications that talk to the outside world without using an external crystal (or its accompanying power requirement).
- Extended Watchdog Timer (WDT): This
 Enhanced version incorporates a 16-bit prescaler,
 allowing an extended time-out range that is stable
 across operating voltage and temperature. See
 Section 4.0 "Electrical Characteristics" for
 time-out periods.

1.3 Details on Individual Family Members

Devices in the PIC18F2423/2523/4423/4523 family are available in 28-pin and 40/44-pin packages. Block diagrams for the two groups are shown in Figure 1-1 and Figure 1-2.

The devices are differentiated from each other in these ways:

- · Flash Program Memory:
 - PIC18F2423/4423 devices 16 Kbytes
 - PIC18F2523/4523 devices 32 Kbytes
- · A/D Channels:
 - PIC18F2423/2523 devices 10
 - PIC18F4423/4523 devices 13
- I/O Ports:
 - PIC18F2423/2523 devices Three bidirectional ports
 - PIC18F4423/4523 devices Five bidirectional ports
- CCP and Enhanced CCP Implementation:
 - PIC18F2423/2523 devices Two standard CCP modules
 - PIC18F4423/4523 devices One standard CCP module and one ECCP module
- Parallel Slave Port Present only on PIC18F4423/4523 devices

All other features for devices in this family are identical. These are summarized in Table 1-1.

The pinouts for all devices are listed in Table 1-2 and Table 1-3.

Members of the PIC18F2423/2523/4423/4523 family are available only as low-voltage devices, designated by "LF" (such as PIC18**LF**2423), and function over an extended VDD range of 2.0V to 5.5V.

TABLE 1-2: PIC18F2423/2523 PINOUT I/O DESCRIPTIONS (CONTINUED)

	Pin N	umber	Pin	Buffer	
Pin Name	PDIP, SOIC	QFN	Туре	Type	Description
					PORTA is a bidirectional I/O port.
RA0/AN0	2	27			
RA0			I/O	TTL	Digital I/O.
AN0			I	Analog	Analog Input 0.
RA1/AN1	3	28			
RA1			I/O	TTL	Digital I/O.
AN1			I	Analog	Analog Input 1.
RA2/AN2/VREF-/CVREF	4	1			
RA2			I/O	TTL	Digital I/O.
AN2			I	Analog	Analog Input 2.
VREF-			I	Analog	A/D reference voltage (low) input.
CVREF			0	Analog	Comparator reference voltage output.
RA3/AN3/VREF+	5	2			
RA3			I/O	TTL	Digital I/O.
AN3			I	Analog	Analog Input 3.
VREF+			I	Analog	A/D reference voltage (high) input.
RA4/T0CKI/C1OUT	6	3			
RA4			I/O	ST	Digital I/O.
T0CKI			I	ST	Timer0 external clock input.
C1OUT			0	_	Comparator 1 output.
RA5/AN4/SS/HLVDIN/	7	4			
C2OUT					
RA5			I/O	TTL	Digital I/O.
AN4			1	Analog	Analog Input 4.
SS			!	TTL	SPI slave select input.
HLVDIN				Analog	
C2OUT			0	_	Comparator 2 output.
RA6					See the OSC2/CLKO/RA6 pin.
RA7					See the OSC1/CLKI/RA7 pin.

Legend: TTL = TTL compatible input CMOS = CMOS compatible input or output

ST = Schmitt Trigger input with CMOS levels I = Input
O = Output P = Power

 $I^2C = I^2C^{\dagger M}/SMBus$

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-2: PIC18F2423/2523 PINOUT I/O DESCRIPTIONS (CONTINUED)

	Pin N	umber	Pin	Buffer	
Pin Name	PDIP, SOIC	QFN	Туре	Туре	Description
					PORTB is a bidirectional I/O port. PORTB can be software programmed for internal weak pull-ups on all inputs.
RB0/INT0/FLT0/AN12 RB0	21	18	I/O	TTL	Digital I/O.
INTO FLTO AN12			 	ST ST Analog	External Interrupt 0. PWM Fault input for CCP1. Analog Input 12.
RB1/INT1/AN10 RB1	22	19	I/O	TTL	Digital I/O.
INT1 AN10			l I	ST Analog	External Interrupt 1. Analog Input 10.
RB2/INT2/AN8 RB2 INT2 AN8	23	20	I/O I	TTL ST Analog	Digital I/O. External Interrupt 2. Analog Input 8.
RB3/AN9/CCP2 RB3 AN9 CCP2 ⁽¹⁾	24	21	I/O I I/O	TTL Analog ST	Digital I/O.
RB4/KBI0/AN11 RB4 KBI0	25	22	I/O I	TTL TTL	Digital I/O. Interrupt-on-change pin.
AN11 RB5/KBI1/PGM	26	23	l I	Analog	,
RB5 KBI1 PGM	20	23	I/O I I/O	TTL TTL ST	Digital I/O. Interrupt-on-change pin. Low-Voltage ICSP™ Programming enable pin.
RB6/KBI2/PGC RB6 KBI2 PGC	27	24	I/O I I/O	TTL TTL ST	Digital I/O. Interrupt-on-change pin. In-Circuit Debugger and ICSP programming clock pin.
RB7/KBI3/PGD RB7 KBI3 PGD	28	25	I/O I I/O	TTL TTL ST	Digital I/O. Interrupt-on-change pin. In-Circuit Debugger and ICSP programming data pin.

Legend: TTL = TTL compatible input

CMOS = CMOS compatible input or output

ST = Schmitt Trigger input with CMOS levels

I = Input

O = Output

P = Power

 $I^2C = I^2C^{\dagger M}/SMBus$

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

TABLE 1-3: PIC18F4423/4523 PINOUT I/O DESCRIPTIONS

Pin Name	Piı	n Numb	er	Pin	Buffer	Description
PIII Name	PDIP	QFN	TQFP	Type	Type	Description
MCLR/VPP/RE3 MCLR	1	18	18	I	ST	Master Clear (input) or programming voltage (input). Master Clear (Reset) input. This pin is an active-low Reset to the device.
VPP				Р		Programming voltage input.
RE3				I	ST	Digital input.
OSC1/CLKI/RA7 OSC1	13	32	30	I	ST	Oscillator crystal or external clock input. Oscillator crystal input or external clock source input. ST buffer when configured in RC mode;
CLKI				I	CMOS	analog otherwise. External clock source input. Always associated with pin function, OSC1. (See related OSC1/CLKI, OSC2/CLKO pins.)
RA7				I/O	TTL	General purpose I/O pin.
OSC2/CLKO/RA6 OSC2	14	33	31	0	_	Oscillator crystal or clock output. Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode.
CLKO				0	_	In RC mode, OSC2 pin outputs CLKO, which has 1/4 the frequency of OSC1 and denotes the instruction cycle rate.
RA6				I/O	TTL	General purpose I/O pin.

Legend: TTL = TTL compatible input

ST = Schmitt Trigger input with CMOS levels

O = Output

 $I^2C = I^2C^{TM}/SMBus$

CMOS = CMOS compatible input or output

I = Input P = Power

Note 1: Default assignment for CCP2 when Configuration bit, CCP2MX, is set.

2: Alternate assignment for CCP2 when Configuration bit, CCP2MX, is cleared.

NOTES:

2.0 12-BIT ANALOG-TO-DIGITAL **CONVERTER (A/D) MODULE**

The Analog-to-Digital (A/D) Converter module has 10 inputs for the PIC18F2423/2523 devices and 13 for the PIC18F4423/4523 devices. This module allows conversion of an analog input signal to a corresponding 12-bit digital number.

The module has five registers:

- A/D Result High Register (ADRESH)
- A/D Result Low Register (ADRESL)
- A/D Control Register 0 (ADCON0)
- A/D Control Register 1 (ADCON1)
- A/D Control Register 2 (ADCON2)

Of the ADCONx registers:

- ADCON0 (shown in Register 2-1) Controls the module's operation
- · ADCON1 (Register 2-2) Configures the functions of the port pins
- ADCON2 (Register 2-3) Configures the A/D clock source, programmed acquisition time and justification

REGISTER 2-1: ADCON0: A/D CONTROL REGISTER 0

U-0	U-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0
_	_	CHS3	CHS2	CHS1	CHS0	GO/DONE	ADON
bit 7							bit 0

Legend:			
R = Readable bit	W = Writable bit	U = Unimplemented bit	, read as '0'
-n = Value at POR	'1' = Bit is set	'0' = Bit is cleared	x = Bit is unknown

bit 7-6 Unimplemented: Read as '0'

bit 5-2 CHS<3:0>: Analog Channel Select bits

0000 = Channel 0 (AN0)

0001 = Channel 1 (AN1)

0010 = Channel 2 (AN2)

0011 = Channel 3 (AN3)

0100 = Channel 4 (AN4)

0101 = Channel 5 (AN5)(1,2) 0110 = Channel 6 (AN6)(1,2)

0111 = Channel 7 (AN7)(1,2)

1000 = Channel 8 (AN8)

1001 = Channel 9 (AN9)

1010 = Channel 10 (AN10)

1011 = Channel 11 (AN11)

1100 = Channel 12 (AN12

1101 = Unimplemented⁽²⁾

1110 = Unimplemented⁽²⁾ 1111 = Unimplemented⁽²⁾

bit 1 GO/DONE: A/D Conversion Status bit

When ADON = 1:

1 = A/D conversion in progress

0 = A/D Idle

bit 0 ADON: A/D On bit

1 = A/D Converter module is enabled

0 = A/D Converter module is disabled

Note 1: These channels are not implemented on PIC18F2423/2523 devices.

Performing a conversion on unimplemented channels will return a floating input measurement.

2.2 Selecting and Configuring Acquisition Time

The ADCON2 register allows the user to select an acquisition time that occurs each time the GO/DONE bit is set. It also gives users the option of having an automatically determined acquisition time.

Acquisition time may be set with the ACQT<2:0> bits (ADCON2<5:3>), which provide a range of 2 to 20 TAD. When the GO/DONE bit is set, the A/D module continues to sample the input for the selected acquisition time, then automatically begins a conversion. Since the acquisition time is programmed, there may be no need to wait for an acquisition time between selecting a channel and setting the GO/DONE bit.

Manual acquisition time is selected when ACQT<2:0> = 000. When the GO/DONE bit is set, sampling is stopped and a conversion begins. The user is responsible for ensuring the required acquisition time has passed between selecting the desired input channel and setting the GO/DONE bit. This option is also the default Reset state of the ACQT<2:0> bits and is compatible with devices that do not offer programmable acquisition times.

In either case, when the conversion is completed, the GO/DONE bit is cleared, the ADIF flag is set and the A/D begins sampling the currently selected channel again. If an acquisition time is programmed, there is nothing to indicate if the acquisition time has ended or if the conversion has begun.

2.3 Selecting the A/D Conversion Clock

The A/D conversion time per bit is defined as TAD. The A/D conversion requires 13 TAD per 12-bit conversion. The source of the A/D conversion clock is software selectable.

There are seven possible options for TAD:

2 Tosc4 Tosc64 Tosc

8 Tosc
 Internal RC Oscillator

16 Tosc

For correct A/D conversions, the A/D conversion clock (TAD) must be as short as possible, but greater than the minimum TAD. (For more information, see parameter 130 on page 41.)

Table 2-2 shows the resultant TAD times derived from the device operating frequencies and the A/D clock source selected.

TABLE 2-2: TAD vs. DEVICE OPERATING FREQUENCIES

A/D Clock So	A/D Clock Source (TAD)					
Operation	ADCS<2:0>	Maximum Fosc				
2 Tosc	000	2.50 MHz				
4 Tosc	100	5.00 MHz				
8 Tosc	001	10.00 MHz				
16 Tosc	101	20.00 MHz				
32 Tosc	010	40.00 MHz				
64 Tosc	110	40.00 MHz				
RC ⁽²⁾	x11	1.00 MHz ⁽¹⁾				

Note 1: The RC source has a typical TAD time of 2.5 μ s.

2: For device frequencies above 1 MHz, the device must be in Sleep for the entire conversion or a Fosc divider should be used instead; otherwise, the A/D accuracy specification may not be met.

2.4 Operation in Power-Managed Modes

The selection of the automatic acquisition time and A/D conversion clock is determined in part by the clock source and frequency while in a power-managed mode.

If the A/D is expected to operate while the device is in a power-managed mode, the ADCS<2:0> bits in ADCON2 should be updated in accordance with the clock source to be used. The ACQT<2:0> bits do not need to be adjusted as the ADCS<2:0> bits adjust the TAD time for the new clock speed. After entering the mode, an A/D acquisition or conversion may be started. Once started, the device should continue to be clocked by the same clock source until the conversion has been completed.

If desired, the device may be placed into the corresponding Idle mode during the conversion. If the device clock frequency is less than 1 MHz, the A/D RC clock source should be selected.

Operation in Sleep mode requires the A/D FRC clock to be selected. If bits, ACQT<2:0>, are set to '000' and a conversion is started, the conversion will be delayed one instruction cycle to allow execution of the SLEEP instruction and entry to Sleep mode. The IDLEN bit (OSCCON<7>) must have already been cleared prior to starting the conversion.

2.5 Configuring Analog Port Pins

The ADCON1, TRISA, TRISB and TRISE registers all configure the A/D port pins. The port pins needed as analog inputs must have their corresponding TRIS bits set (input). If the TRIS bit is cleared (output), the digital output level (VOH or VOL) will be converted.

The A/D operation is independent of the state of the CHS<3:0> bits and the TRIS bits.

- Note 1: When reading the PORT register, all pins configured as analog input channels will read as cleared (a low level). Analog conversion on pins configured as digital pins can be performed. The voltage on the pin will be accurately converted.
 - 2: Analog levels on any pin defined as a digital input may cause the digital input buffer to consume current out of the device's specification limits.
 - **3:** The PBADEN bit in Configuration Register 3H configures PORTB pins to reset as analog or digital pins by controlling how the PCFG<3:0> bits in ADCON1 are reset.

2.8 Use of the CCP2 Trigger

An A/D conversion can be started by the Special Event Trigger of the CCP2 module. This requires that the CCP2M<3:0> bits (CCP2CON<3:0>) be programmed as '1011' and that the A/D module is enabled (ADON bit is set). When the trigger occurs, the GO/DONE bit will be set, starting the A/D acquisition and conversion, and the Timer1 (or Timer3) counter will be reset to zero. Timer1 (or Timer3) is reset to automatically repeat the A/D acquisition period with minimal software overhead (moving ADRESH:ADRESL to the desired location).

The appropriate analog input channel must be selected and the minimum acquisition period is either timed by the user or an appropriate TACQ time is selected before the Special Event Trigger sets the GO/DONE bit (starts a conversion).

If the A/D module is not enabled (ADON is cleared), the Special Event Trigger will be ignored by the A/D module, but will still reset the Timer1 (or Timer3) counter.

TABLE 2-3: REGISTERS ASSOCIATED WITH A/D OPERATION

Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Reset Values on page
INTCON	GIE/GIEH	PEIE/GIEL	TMR0IE	INT0IE	RBIE	TMR0IF	INT0IF	RBIF	(Note 4)
PIR1	PSPIF ⁽¹⁾	ADIF	RCIF	TXIF	SSPIF	CCP1IF	TMR2IF	TMR1IF	(Note 4)
PIE1	PSPIE ⁽¹⁾	ADIE	RCIE	TXIE	SSPIE	CCP1IE	TMR2IE	TMR1IE	(Note 4)
IPR1	PSPIP ⁽¹⁾	ADIP	RCIP	TXIP	SSPIP	CCP1IP	TMR2IP	TMR1IP	(Note 4)
PIR2	OSCFIF	CMIF	_	EEIF	BCLIF	HLVDIF	TMR3IF	CCP2IF	(Note 4)
PIE2	OSCFIE	CMIE	_	EEIE	BCLIE	HLVDIE	TMR3IE	CCP2IE	(Note 4)
IPR2	OSCFIP	CMIP	_	EEIP	BCLIP	HLVDIP	TMR3IP	CCP2IP	(Note 4)
ADRESH	A/D Result	Register Hig	gh Byte						(Note 4)
ADRESL	A/D Result	Register Lo	w Byte						(Note 4)
ADCON0	_	_	CHS3	CHS2	CHS1	CHS0	GO/DONE	ADON	(Note 4)
ADCON1	_	_	VCFG1	VCFG0	PCFG3	PCFG2	PCFG1	PCFG0	(Note 4)
ADCON2	ADFM	_	ACQT2	ACQT1	ACQT0	ADCS2	ADCS1	ADCS0	(Note 4)
PORTA	RA7 ⁽²⁾	RA6 ⁽²⁾	RA5	RA4	RA3	RA2	RA1	RA0	(Note 4)
TRISA	TRISA7 ⁽²⁾	TRISA6 ⁽²⁾	PORTA Da	ata Direction	Control Re	gister			(Note 4)
PORTB	RB7	RB6	RB5	RB4	RB3	RB2	RB1	RB0	(Note 4)
TRISB	PORTB Dat	a Direction (Control Reg	ister					(Note 4)
LATB	PORTB Dat	a Latch Reg	egister (Read and Write to Data Latch)				(Note 4)		
PORTE ⁽¹⁾	_	_	_	_	RE3 ⁽³⁾	RE2	RE1	RE0	(Note 4)
TRISE ⁽¹⁾	IBF	OBF	IBOV	PSPMODE	_	TRISE2	TRISE1	TRISE0	(Note 4)
LATE ⁽¹⁾	_	_		_	_	PORTE D	ata Latch Re	gister	(Note 4)

Legend: — = unimplemented, read as '0'. Shaded cells are not used for A/D conversion.

- Note 1: These registers and/or bits are not implemented on PIC18F2423/2523 devices and are read as '0'.
 - 2: PORTA<7:6> and their direction bits are individually configured as port pins based on various primary oscillator modes. When disabled, these bits read as '0'.
 - 3: RE3 port bit is available only as an input pin when the MCLRE Configuration bit is '0'.
 - **4:** For these Reset values, see **Section 4.0 "Reset"** of the "*PIC18F2420/2520/4420/4520 Data Sheet"* (DS39631).

REGISTER 3-2: DEVID2: DEVICE ID REGISTER 2 FOR PIC18F2423/2523/4423/4523

R	R	R	R	R	R	R	R
DEV11 ⁽¹⁾	DEV10 ⁽¹⁾	DEV9 ⁽¹⁾	DEV8 ⁽¹⁾	DEV7 ⁽¹⁾	DEV6 ⁽¹⁾	DEV5 ⁽¹⁾	DEV4 ⁽¹⁾
bit 7							bit 0

Legend:

R = Read-only bit P = Programmable bit U = Unimplemented bit, read as '0'
-n = Value when device is unprogrammed u = Unchanged from programmed state

bit 7-0 **DEV<11:4>:** Device ID bits⁽¹⁾

These bits are used with the DEV<3:0> bits in Device ID Register 1 to identify the part number.

0001 0001 = PIC18F2423/2523 devices 0001 0000 = PIC18F4423/4523 devices

Note 1: These values for DEV<11:4> may be shared with other devices. The specific device is always identified by using the entire DEV<11:0> bit sequence.

FIGURE 4-1: PIC18F2423/2523/4423/4523 VOLTAGE-FREQUENCY GRAPH (INDUSTRIAL)

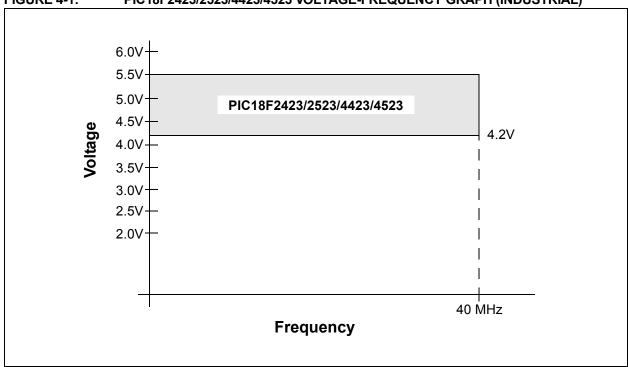
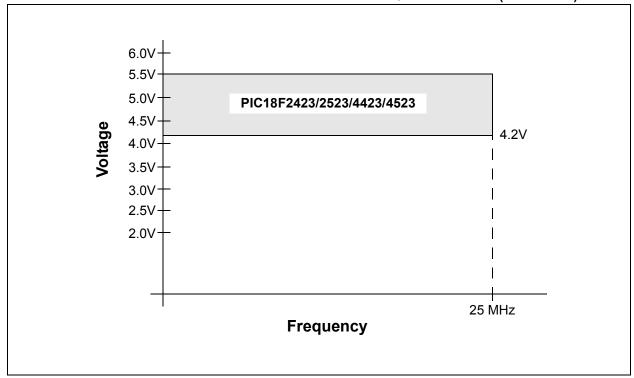


FIGURE 4-2: PIC18F2423/2523/4423/4523 VOLTAGE-FREQUENCY GRAPH (EXTENDED)



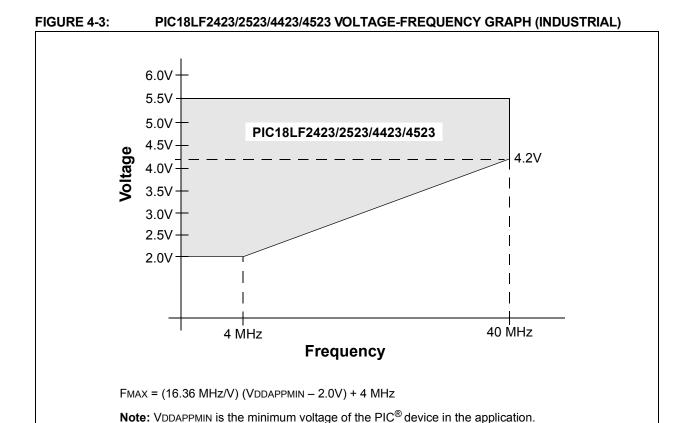


TABLE 4-1: A/D CONVERTER CHARACTERISTICS: PIC18F2423/2523/4423/4523 (INDUSTRIAL) PIC18LF2423/2523/4423/4523 (INDUSTRIAL)

Param No.	Sym	Characteristic	Min	Тур	Max	Units		Conditions
A01	NR	Resolution	_	_	12	bit		ΔV REF $\geq 3.0V$
A03	EIL	Integral Linearity Error	_	<±1	±2.0	LSB	VDD = 3.0V	$\Delta VREF \ge 3.0V$
			_	_	±2.0	LSB	VDD = 5.0V	
A04	EDL	Differential Linearity Error	_	<±1	+1.5/-1.0	LSB	VDD = 3.0V	ΔV REF $\geq 3.0V$
			_	_	+1.5/-1.0	LSB	VDD = 5.0V	
A06	Eoff	Offset Error	_	<±1	±5	LSB	VDD = 3.0V	ΔV REF $\geq 3.0V$
			_	_	±3	LSB	VDD = 5.0V	
A07	Egn	Gain Error	_	<±1	±1.25	LSB	VDD = 3.0V	ΔV REF $\geq 3.0V$
			_	_	±2.00	LSB	VDD = 5.0V	
A10	_	Monotonicity	Gı	uarantee	d ⁽¹⁾	_		$Vss \leq Vain \leq Vref$
A20	ΔVREF	Reference Voltage Range (VREFH – VREFL)	3	_	VDD - VSS	V		For 12-bit resolution.
A21	VREFH	Reference Voltage High	Vss + 3.0V	_	VDD + 0.3V	V		For 12-bit resolution.
A22	VREFL	Reference Voltage Low	Vss - 0.3V	_	VDD - 3.0V	V		For 12-bit resolution.
A25	Vain	Analog Input Voltage	VREFL	_	VREFH	V		
A30	ZAIN	Recommended Impedance of Analog Voltage Source	_	_	2.5	kΩ		
A50	IREF	VREF Input Current ⁽²⁾	_	_ _	5 150	μ Α μ Α		During VAIN acquisition. During A/D conversion cycle.

Note 1: The A/D conversion result never decreases with an increase in the input voltage and has no missing codes.

^{2:} VREFH current is from the RA3/AN3/VREF+ pin or VDD, whichever is selected as the VREFH source. VREFL current is from the RA2/AN2/VREF-/CVREF pin or VSs, whichever is selected as the VREFL source.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. Device	X /XX XXX Temperature Package Pattern Range	Examples: a) PIC18F4523-I/P 301 = Industrial temp., PDIP package, Extended VDD limits, QTP pattern #301. b) PIC18F4523-I/PT = Industrial temp., TQFP
Device	PIC18F2423 ⁽¹⁾ , PIC18F2523 ⁽¹⁾ , PIC18F4423T ⁽²⁾ , PIC18F4523T ⁽²⁾ ; VDD range 4.2V to 5.5V PIC18F2423 ⁽¹⁾ , PIC18F2523 ⁽¹⁾ , PIC18F4423T ⁽²⁾ , PIC18F4523T ⁽²⁾ ; VDD range 2.0V to 5.5V	package, Extended VDD limits. c) PIC18F4523-E/P = Extended temp., PDIP package, normal VDD limits.
Temperature Range	I = -40 °C to $+85$ °C (Industrial) E = -40 °C to $+125$ °C (Extended)	
Package	PT = TQFP (Thin Quad Flat pack) ML = QFN SO = SOIC SP = Skinny Plastic DIP P = PDIP	Note 1: F = Standard Voltage Range LF = Wide Voltage Range 2: T = In tape and reel PLCC, and TQFP packages only.
Pattern	QTP, SQTP, Code or Special Requirements (blank otherwise)	